Surface Mount Transient Voltage Suppressor Diode Array

Features

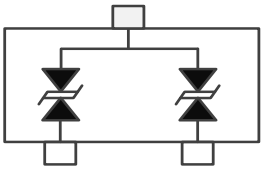
- ESD protection of two I/O lines
- Solid-state silicon-avalanche technology
- Working Voltage: 5.0V
- Peak Power up to 36 Watts @ 8 x 20μs Pulse
- Low Leakage current
- Response Time is Typically < 1 ns
- IEC 61000-4-2 (ESD) ±25kV (air), ±25kV (contact)
- IEC 61000-4-4 (EFT) 40A (5/50ns)

Applications

- Cellular Handsets & Accessories
- Portable devices
- Dataline
- Computer&Notebook

Mechanical Data

- UL Flame Rating : UL94V-0
- Reel Size : 7 inch
- RoHS/WEEE Compliant



Circuit Diagram



SOT-23

Absolute Maximum Rating at T_A = 25 °C, unless otherwise specified

Rating	Symbol	Value	Units
Peak Pulse Power (t_p =8/20μs)	P_{PP}	36	Watts
Peak Pulse Current (t_p =8/20μs) (note1)	I_{pp}	3.0	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	±25 ±25	kV
Lead Soldering Temperature	T_L	260(10seconds)	℃
Junction Temperature	T_J	-55 to + 125	℃
Storage Temperature	T_{stg}	-55 to + 150	℃

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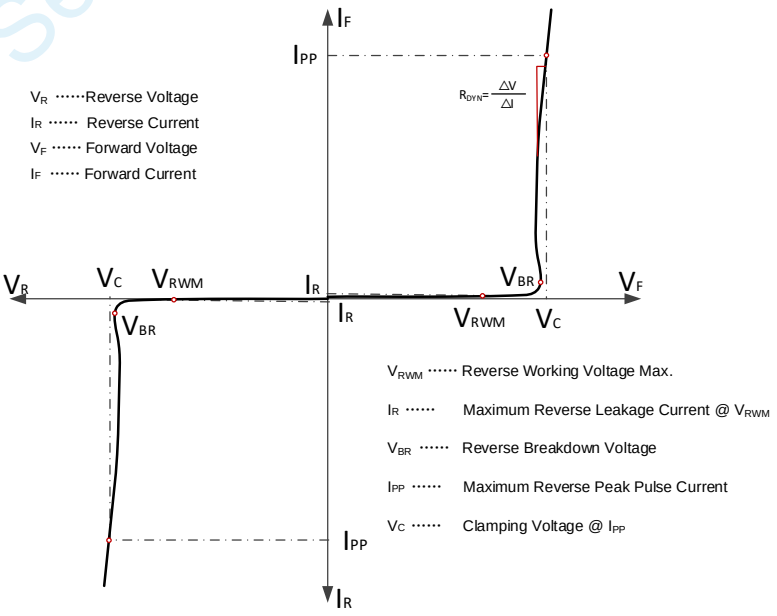
Electrical Characteristics at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Conditions		Min.	Typical	Max.	Units
Reverse Stand-Off Voltage	V_{RWM}					5.0	V
Reverse Breakdown Voltage	V_{BR}	I_T=1mA		5.6			V
Reverse Leakage Current	I_R	V_{RWM}=5.0V, T=25℃				1.0	μA
Peak Pulse Current	I_{PP}	tp =8/20μs				3.0	A
Clamping Voltage	V_C	I_{PP}=1A, tp=8/20μs			7.8	8.5	V
Clamping Voltage	V_C	I_{PP}=3.0A, tp=8/20μs			10	12	V
Junction Capacitance	C_J	V_R = 0V, f = 1MHz	I/O to I/O		1.5	2.0	pF
			Pin1/2 to Pin3		3.1	3.7	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
1. All parameters specified at T_A = 25°C unless otherwise noted.
2. These parameters are guaranteed by design and characterization.
3. Standard IEC 61000−4−2 with $C_{Discharge}$ = 150 pF, $R_{Discharge}$ = 330 Ω

Electrical Parameters at T_A = 25 °C, unless otherwise specified



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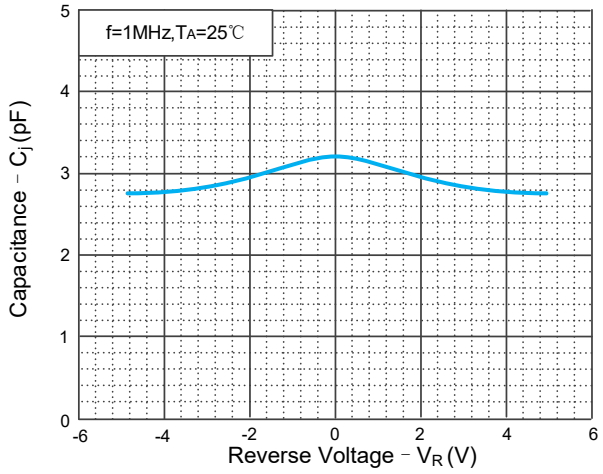
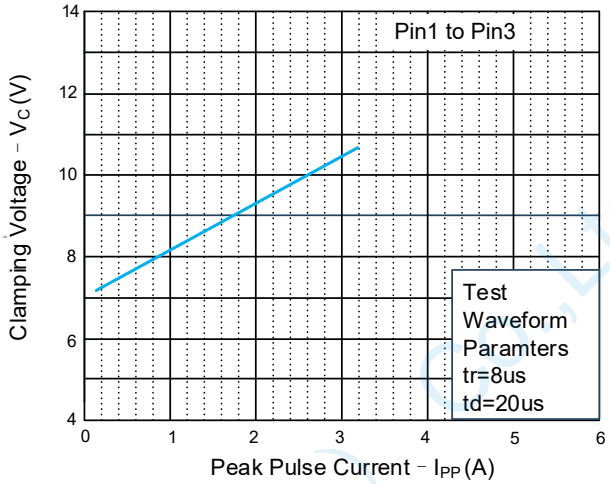
Typical Characteristics at T_A = 25 °C, unless otherwise specified

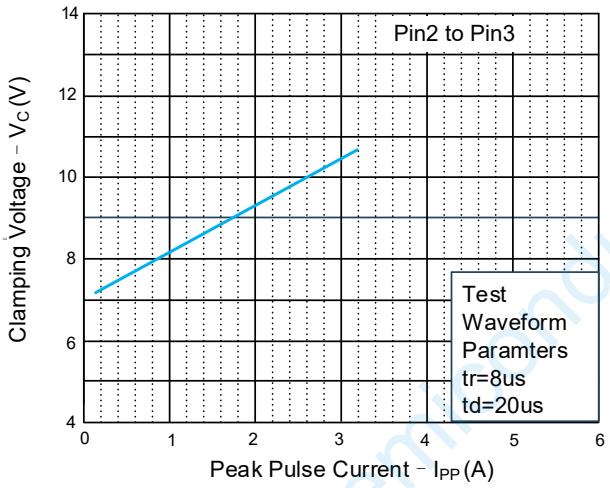
Capacitance vs. Reverse Voltage



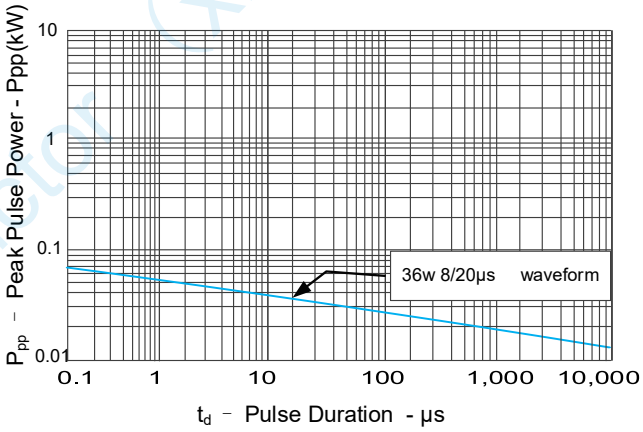
Reverse Clamping Voltage vs. Peak Pulse Current



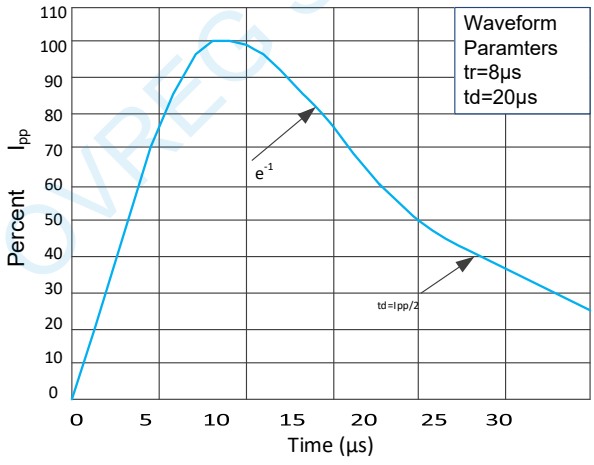
Forward Clamping Voltage vs. peak PulseCurrent



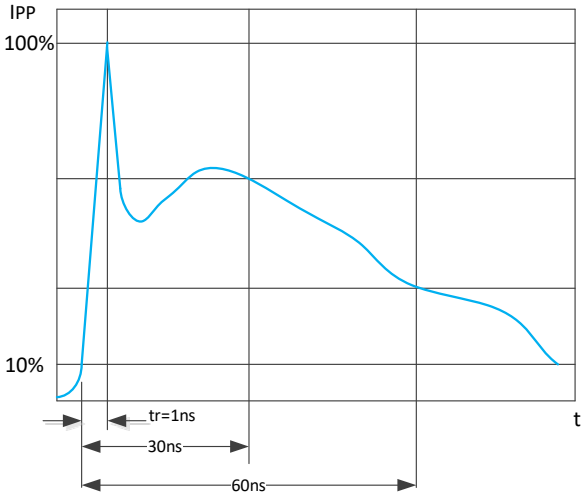
Non-repetitive Peak Pulse Power vs. Pulse Time



8/20uS Pulse Waveform



IEC61000-4-2 +8kV Pulse Waveform



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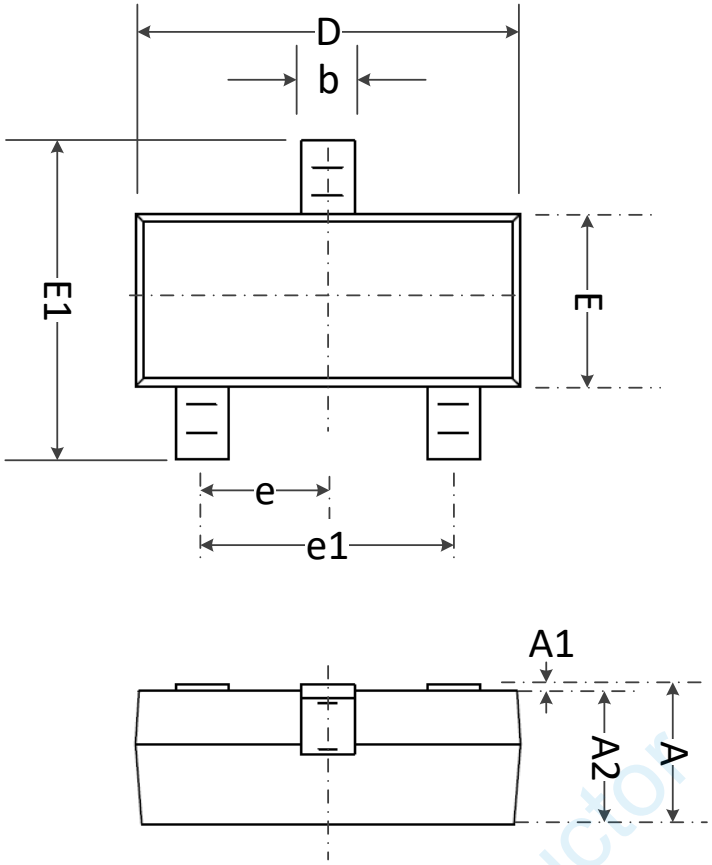
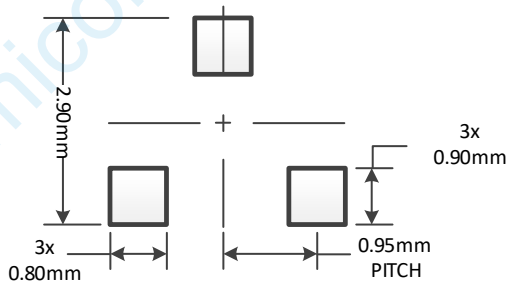
Package information



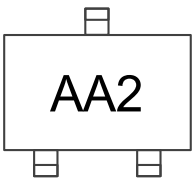
COMMON DIMENSION (MM)			
PKG	SOT23		
REF.	MIN.	NOM.	MAX.
A	0.90	-	1.15
A1	0.00	-	0.10
A2	0.90	1.00	1.05
b	0.30	-	0.50
c	0.08	-	0.15
D	2.80	2.90	3.00
E	1.20	1.30	1.40
E1	2.25	2.40	2.55
e	0.95TYP		
e1	1.80	1.90	2.00
L	0.55REF		
L1	0.30	0.45	0.50

Recommend PCB Layout



Notes: This PCB Layout Is For Reference Purposes Only

Marking



Ordering Information

Part number	Material	Type	Reel size	MOQ	MOQ/internal box	MOQ/carton
OVE1425A1	GREEN	T/R	7 inch	3k/reel	10reel= 30k/box	4boxes=120k/carton

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